



Burr-Brown Products  
from Texas Instruments



**TMP125**

SBOS323A – DECEMBER 2004 – REVISED JUNE 2005

## 2°C Accurate Digital Temperature Sensor with SPI™ Interface

### FEATURES

- **DIGITAL OUTPUT: SPI-Compatible Interface**
- **RESOLUTION: 10-Bit, 0.25°C**
- **ACCURACY:**  
±2.0°C (max) from -25°C to +85°C  
±2.5°C (max) from -40°C to +125°C
- **LOW QUIESCENT CURRENT: 50µA (max)**
- **WIDE SUPPLY RANGE: 2.7V to 5.5V**
- **TINY SOT23-6 PACKAGE**
- **OPERATION FROM -40°C to +125°C**

### APPLICATIONS

- **BASE STATION EQUIPMENT**
- **COMPUTER PERIPHERAL THERMAL PROTECTION**
- **NOTEBOOK COMPUTERS**
- **DATA ACQUISITION SYSTEMS**
- **TELECOM EQUIPMENT**
- **OFFICE MACHINES**

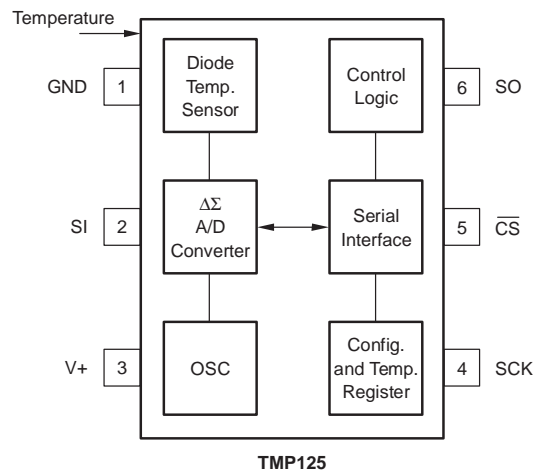
### TMP125 RELATED PRODUCTS

| FEATURES   | PRODUCT    |
|--|------------|
| 2°C Digital Temp Sensors with Two-Wire Interface   | TMP100/101 |
| 1.5°C Digital Temp Sensors with Two-Wire Interface | TMP75/175  |
| 1.5°C Digital Temp Sensors with SPI                | TMP121/123 |
| 1.5°C Programmable Digital Temp Sensors with SPI   | TMP122/124 |

### DESCRIPTION

The TMP125 is an SPI-compatible temperature sensor available in the tiny SOT23-6 package. Requiring no external components, the TMP125 is capable of measuring temperatures within 2°C of accuracy over a temperature range of -25°C to +85°C and 2.5°C of accuracy over -40°C to +125°C. Low supply current, and a supply range from 2.7V to 5.5V, make the TMP125 an excellent candidate for low-power applications.

The TMP125 is ideal for extended thermal measurement in a variety of communication, computer, consumer, environmental, industrial, and instrumentation applications.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SPI is a registered trademark of Motorola. All other trademarks are the property of their respective owners.

**TMP125**



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**ABSOLUTE MAXIMUM RATINGS(1)**

|   |                 |
|---|-----------------|
| Supply Voltage                            | +7V             |
| Input Voltage(2)                          | -0.3V to +7V    |
| Input Current                             | ±10mA           |
| Output Short Circuit(3)                   | Continuous      |
| Operating Temperature Range               | -55°C to +125°C |
| Storage Temperature Range                 | -60°C to +150°C |
| Junction Temperature (T <sub>J</sub> max) | +150°C          |
| Lead Temperature (soldering)              | +300°C          |
| ESD Rating (Human Body Model)             | 4000V           |
| (Charged Device Model)                    | 1000V           |



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

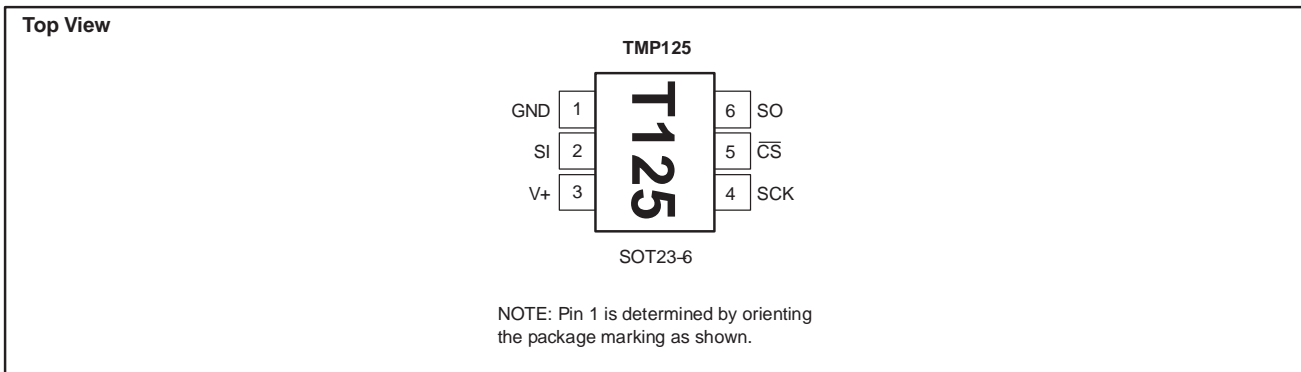
- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not supported.
- (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less.
- (3) Short-circuit to ground.

**ORDERING INFORMATION(1)**

| PRODUCT | PACKAGE-LEAD | PACKAGE DESIGNATOR | PACKAGE MARKING |
|---------|--------------|--------------------|-----------------|
| TMP125  | SOT23-6      | DBV                | T125            |

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).

**PIN CONFIGURATION**





**ELECTRICAL CHARACTERISTICS**

At  $T_A = -40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  and  $V_S = +2.7\text{V}$  to  $5.5\text{V}$ , unless otherwise noted.

| PARAMETER  | CONDITIONS  | TMP125  |           |           | UNIT                        |
|--|---|---|-----------|-----------|-----------------------------|
|  |   | MIN   | TYP       | MAX       |                             |
| <b>TEMPERATURE INPUT</b>                           |   |   |           |           |                             |
| Range  |   | -40   |           | +125      | $^{\circ}\text{C}$          |
| Accuracy (temperature error)                       | -25 $^{\circ}\text{C}$ to +85 $^{\circ}\text{C}$  |   | $\pm 0.5$ | $\pm 2.0$ | $^{\circ}\text{C}$          |
|  | -40 $^{\circ}\text{C}$ to +125 $^{\circ}\text{C}$ |   | $\pm 1.0$ | $\pm 2.5$ | $^{\circ}\text{C}$          |
| Resolution   |   |   | 10        |           | Bits                        |
| Temperature Measurement Noise                      |   |   | 0.1       |           | LSB                         |
| <b>DIGITAL INPUT/OUTPUT</b>                        |   |   |           |           |                             |
| Input Logic Levels:                                |   |   |           |           |                             |
| $V_{IH}$   |   | 0.7(V+)   |           |           | V                           |
| $V_{IL}$   |   |   |           | 0.3(V+)   | V                           |
| Input Current, SI, SCK, $\overline{\text{CS}}$     | $I_{IN}$  | $0\text{V} = V_{IN} = \text{V+}$                  |           | $\pm 1$   | $\mu\text{A}$               |
| Output Logic Levels:                               |   |   |           |           |                             |
| $V_{OL\ SO}$                                       |   | $I_{SINK} = 3\text{mA}$                           |           | 0.4       | V                           |
| $V_{OH\ SO}$                                       |   | $I_{SOURCE} = 2\text{mA}$                         |           |           | V                           |
| Input Capacitance, SI, SCK, $\overline{\text{CS}}$ |   |   | 2.5       |           | pF                          |
| Conversion Time                                    | 10-Bit  |   | 60        |           | ms                          |
| Update Rate  |   |   | 120       |           | ms                          |
| <b>POWER SUPPLY</b>                                |   |   |           |           |                             |
| Operating Range                                    |   | 2.7   |           | 5.5       | V                           |
| Quiescent Current, at $T_A = 25^{\circ}\text{C}$   | $I_Q$   | Serial Bus Inactive                               | 36        | 50        | $\mu\text{A}$               |
| over Temperature                                   |   | -40 $^{\circ}\text{C}$ to +125 $^{\circ}\text{C}$ |           | 60        | $\mu\text{A}$               |
| Shutdown Current                                   |   |   | 0.1       | 1         | $\mu\text{A}$               |
| over Temperature                                   |   |   |           | 1         | $\mu\text{A}$               |
| <b>TEMPERATURE RANGE</b>                           |   |   |           |           |                             |
| Specified Range                                    |   | -40   |           | +125      | $^{\circ}\text{C}$          |
| Operating Range                                    |   | -55   |           | +125      | $^{\circ}\text{C}$          |
| Storage Range                                      |   | -60   |           | +150      | $^{\circ}\text{C}$          |
| Thermal Resistance                                 | $\theta_{JA}$                                     | SOT23-6 Surface-Mount                             | 200       |           | $^{\circ}\text{C}/\text{W}$ |

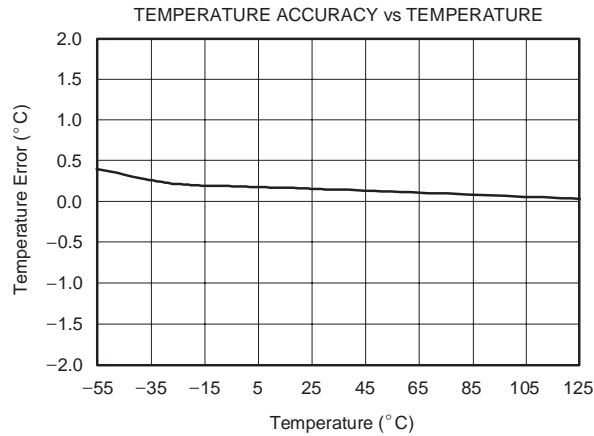
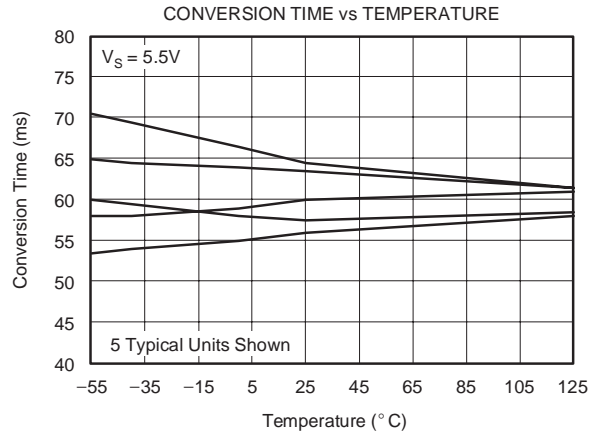
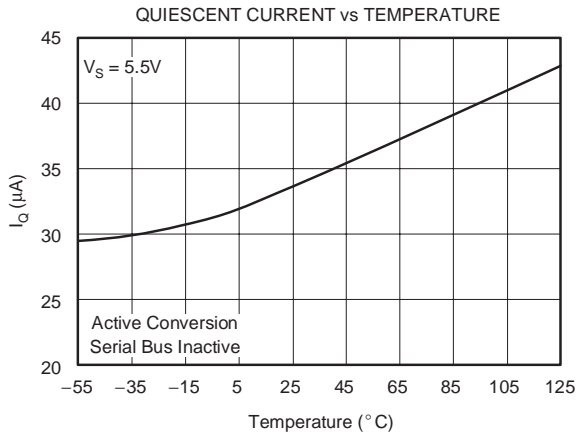
**TMP125**



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**TYPICAL CHARACTERISTICS**

At  $T_A = -40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  and  $V_S = +2.7\text{V}$  to  $5.5\text{V}$ , unless otherwise noted.



## APPLICATIONS

The TMP125 10-bit, read-only digital temperature sensor is optimal for thermal management and thermal protection applications. The TMP125 is specified for a temperature range of  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ , with operation extending down to  $-55^{\circ}\text{C}$ . It is specified for a supply voltage range of 2.7V to 5.5V, and also features a hardware shutdown to provide power savings. Quiescent current is reduced to  $1\mu\text{A}$  during analog shutdown.

The TMP125 communicates through a serial interface that is SPI-compatible. Temperature is converted to a 10-bit data word with  $0.25^{\circ}\text{C}$  resolution. The TMP125 is optimal for low-power applications, with a 120ms conversion period for reduced power consumption.

The sensing device of the TMP125 is the chip itself. Thermal paths run through the package leads as well as the plastic package, and the lower thermal resistance of metal causes the leads to provide the primary thermal path.

The TMP125 requires no external components for operation, though a  $0.1\mu\text{F}$  supply bypass capacitor is recommended. Figure 1 shows typical connection for the TMP125.

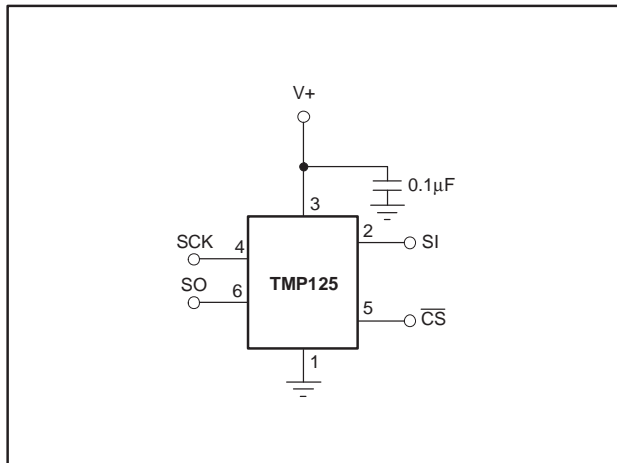


Figure 1. Typical Connections for the TMP125

### COMMUNICATING WITH THE TMP125

The TMP125 continuously converts temperatures to digital data. Temperature data is read by pulling  $\overline{\text{CS}}$  low. Once  $\overline{\text{CS}}$  is pulled low, temperature data from the last completed conversion prior to dropping  $\overline{\text{CS}}$  is latched into the shift register and clocked out at SO on the falling SCK edge. The 16-bit data word is clocked out sign bit first, followed by the MSB. The SI pin is used to put the device into shutdown mode. To enter shutdown mode, SI must be high on the rising edge of the third bit of SCK (see Figure 3). Also, all 16 bits must be clocked to allow shutdown on the TMP125. To bring the device out of

shutdown, perform a 16-clock communication with SI set to logic low. The 16-clock communication is the same as the Data Read shown in Figure 3, except that the data on SO will be the last conversion prior to putting the device into shutdown mode. Note that SO is only used to control the shutdown function; if not using this function, connect this pin to ground.

The one-shot command can be used to force a single conversion. When the command is issued, the part will perform a single conversion and then go into shutdown mode. After the conversion is complete, the conversion result should be read with the power-down bit high (see Figure 3) if you do not want to start a new conversion.

The TMP125 will go into idle mode for 60ms, requiring only  $20\mu\text{A}$  of current. A new conversion begins every 120ms. Figure 2 describes the conversion timing for the TMP125.

### TEMPERATURE REGISTER

The Temperature Register of the TMP125 is a 16-bit, read-only register that stores the output of the most recent conversion. However, temperature is represented by only 10-bits, which are in signed two's complement format. The first bit of the Temperature Register, D15, is a leading zero. Bits D14 and D5 are used to indicate temperature. Bits D4 to D0 are the same as D5 (see Table 1). Data format for temperature is summarized in Table 2. When calculating the signed two's complement temperature value, be sure to use only the 10 data bits.

Following power-up or reset, the Temperature Register will read  $0^{\circ}\text{C}$  until the first conversion is complete.

|     |     |     |     |     |     |    |    |
|-----|-----|-----|-----|-----|-----|----|----|
| D15 | D14 | D13 | D12 | D11 | D10 | D9 | D8 |
| 0   | T9  | T8  | T7  | T6  | T5  | T4 | T3 |
| D7  | D6  | D5  | D4  | D3  | D2  | D1 | D0 |
| T2  | T1  | T0  | T0  | T0  | T0  | T0 | T0 |

Table 1. Temperature Register

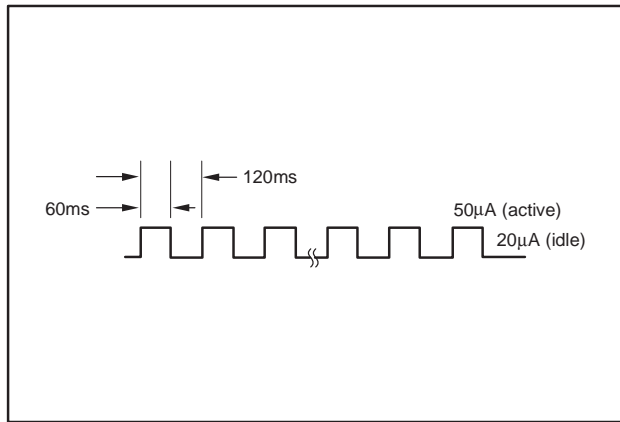
| TEMPERATURE ( $^{\circ}\text{C}$ ) | DIGITAL OUTPUT D14...D5 |
|------------------------------------|-------------------------|
| +127                               | 01 1111 1100            |
| +125                               | 01 1111 0100            |
| +100                               | 01 1001 0000            |
| +75                                | 01 0010 1100            |
| +50                                | 00 1100 1000            |
| +25                                | 00 0110 0100            |
| +10                                | 00 0010 1000            |
| +0.25                              | 00 0000 0001            |
| 0                                  | 00 0000 0000            |
| -0.25                              | 11 1111 1111            |
| -25                                | 11 1001 1100            |
| -50                                | 11 0011 1000            |
| -55                                | 11 0010 0100            |

Table 2. Temperature Data Format

**TMP125**



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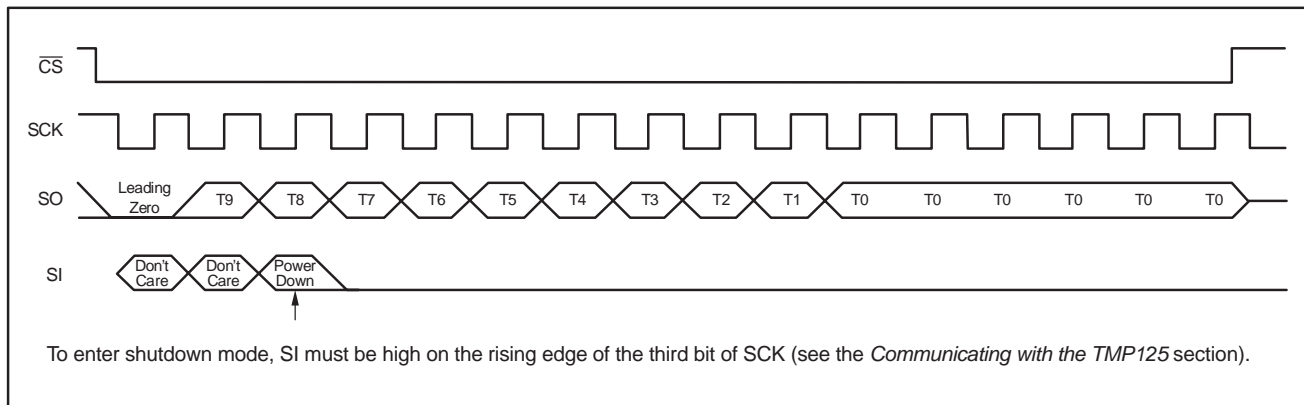
**Figure 2. Conversion Time and Period**

**Timing Diagrams**

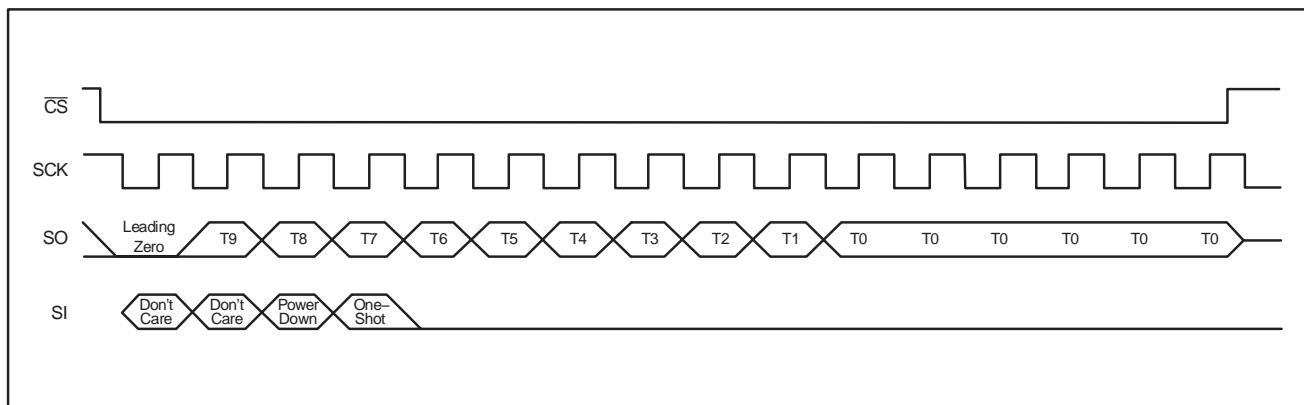
The TMP125 is SPI-compatible. Figure 3 and Figure 4 describe the output data of the TMP125. Figure 5, Figure 6, and Figure 7 describe the various timing requirements, with parameters defined in Table 3.

| PARAMETER  | MIN   | MAX | UNITS |
|--|-------|-----|-------|
| SCK Period   | $t_1$ | 100 | ns    |
| Data In to Rising Edge SCK Setup Time                | $t_2$ | 20  | ns    |
| SCK Falling Edge to Output Data Delay                | $t_3$ | 30  | ns    |
| SCK Rising Edge to Input Data Hold Time              | $t_4$ | 20  | ns    |
| $\overline{CS}$ to Rising Edge SCK Set-Up Time       | $t_5$ | 40  | ns    |
| $\overline{CS}$ to Output Data Delay                 | $t_6$ | 30  | ns    |
| $\overline{CS}$ Rising Edge to Output High Impedance | $t_7$ | 30  | ns    |

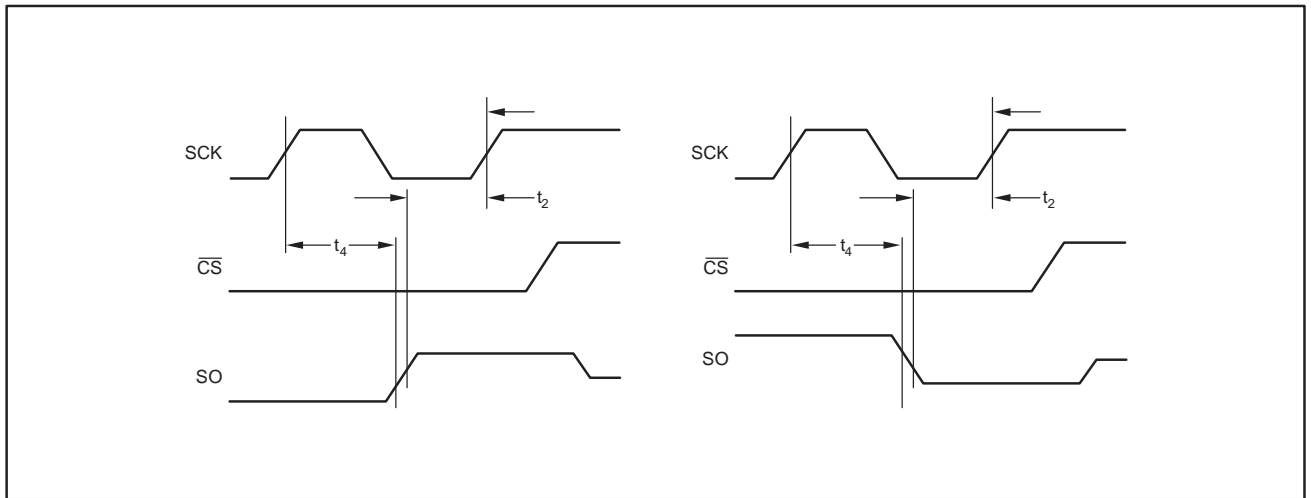
**Table 3. Timing Description**



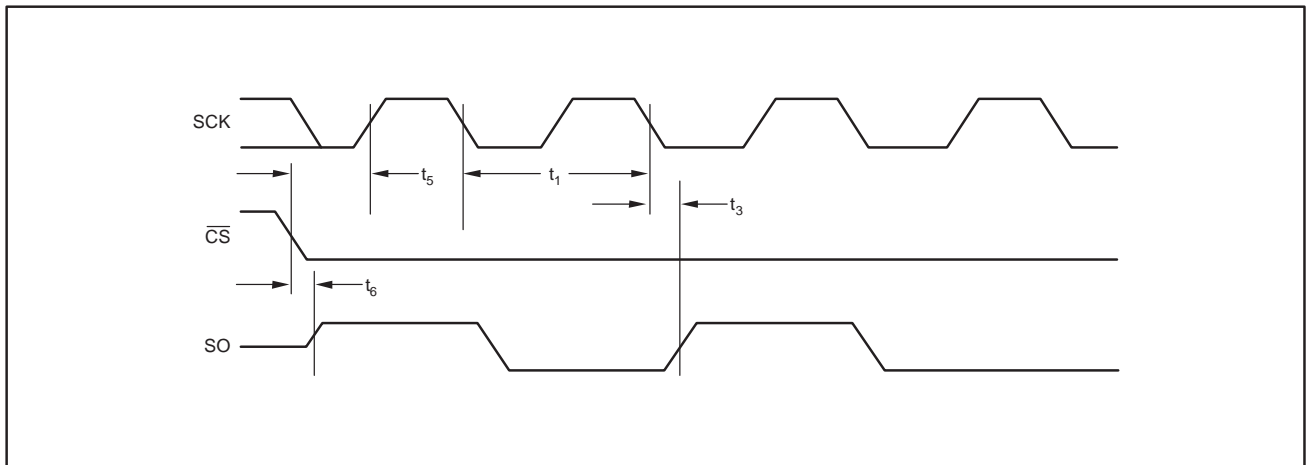
**Figure 3. Data READ**



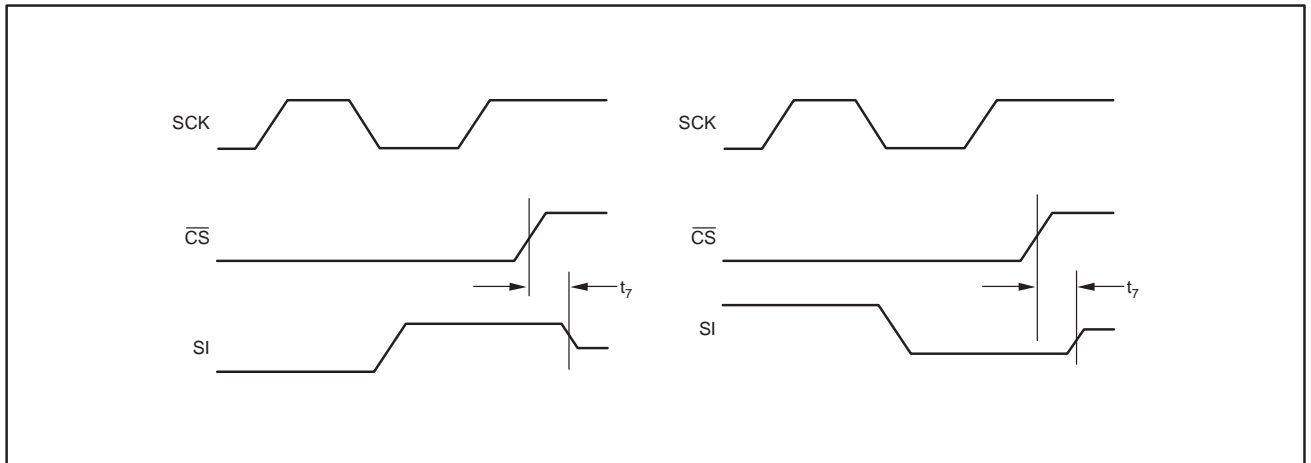
**Figure 4. One-Shot Command**



**Figure 5. Input Data Timing Diagram**



**Figure 6. Output Data Timing Diagram**



**Figure 7. High Impedance Output Timing Diagram**



**PACKAGE OPTION ADDENDUM**

www.ti.com

9-Sep-2014

**PACKAGING INFORMATION**

| Orderable Device | Status<br>(1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan<br>(2)         | Lead/Ball Finish<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5) | Samples                 |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| TMP125AIDBVR     | ACTIVE        | SOT-23       | DBV             | 6    | 3000        | Green (RoHS & no Sb/Br) | CU NIPDAU               | Level-2-260C-1 YEAR  | -40 to 125   | T125                    | <a href="#">Samples</a> |
| TMP125AIDBVRG4   | ACTIVE        | SOT-23       | DBV             | 6    | 3000        | Green (RoHS & no Sb/Br) | CU NIPDAU               | Level-2-260C-1 YEAR  | -40 to 125   | T125                    | <a href="#">Samples</a> |
| TMP125AIDBVT     | ACTIVE        | SOT-23       | DBV             | 6    | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU               | Level-2-260C-1 YEAR  | -40 to 125   | T125                    | <a href="#">Samples</a> |
| TMP125AIDBVTG4   | ACTIVE        | SOT-23       | DBV             | 6    | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU               | Level-2-260C-1 YEAR  | -40 to 125   | T125                    | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.





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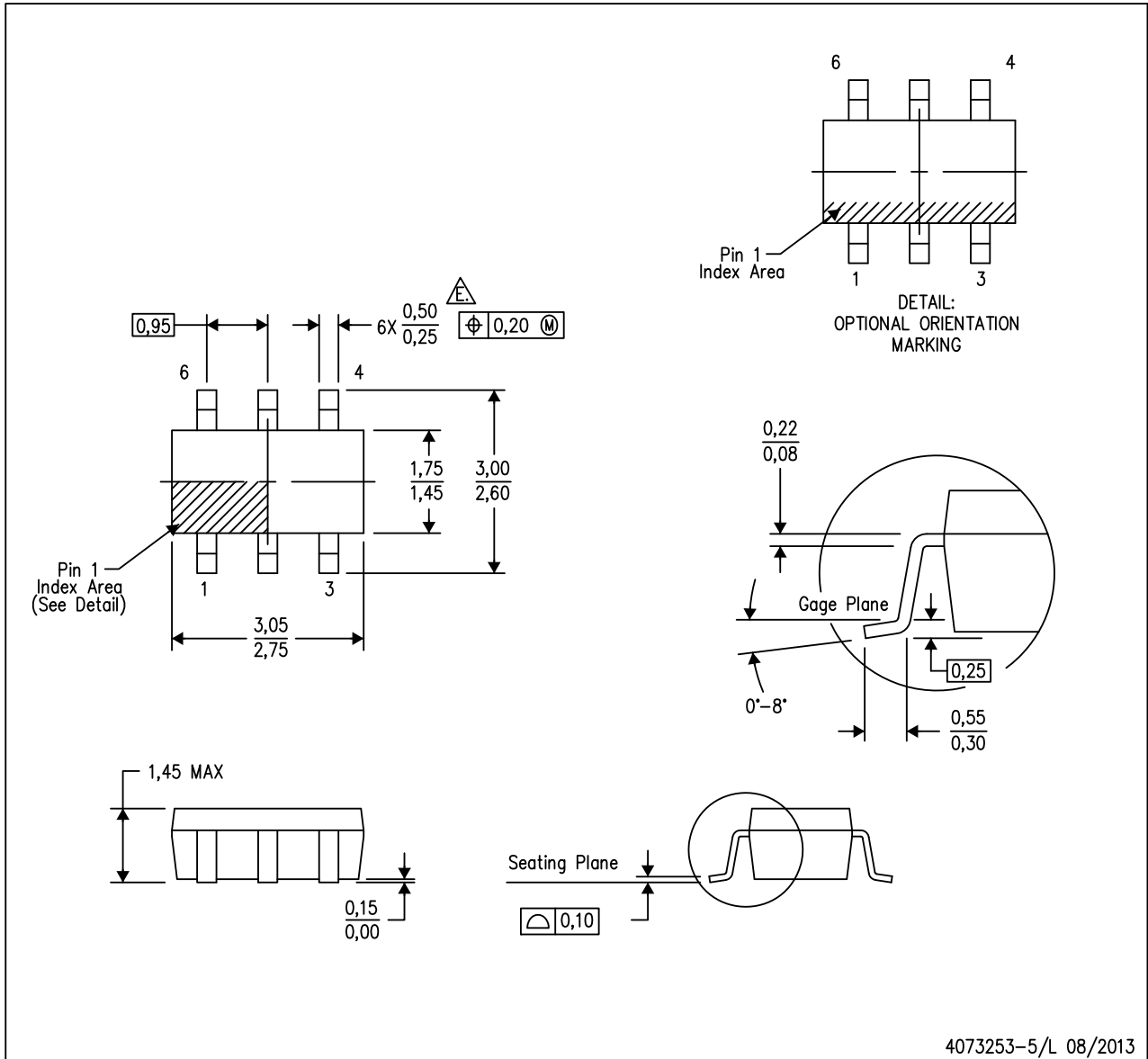
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**MECHANICAL DATA**

DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE

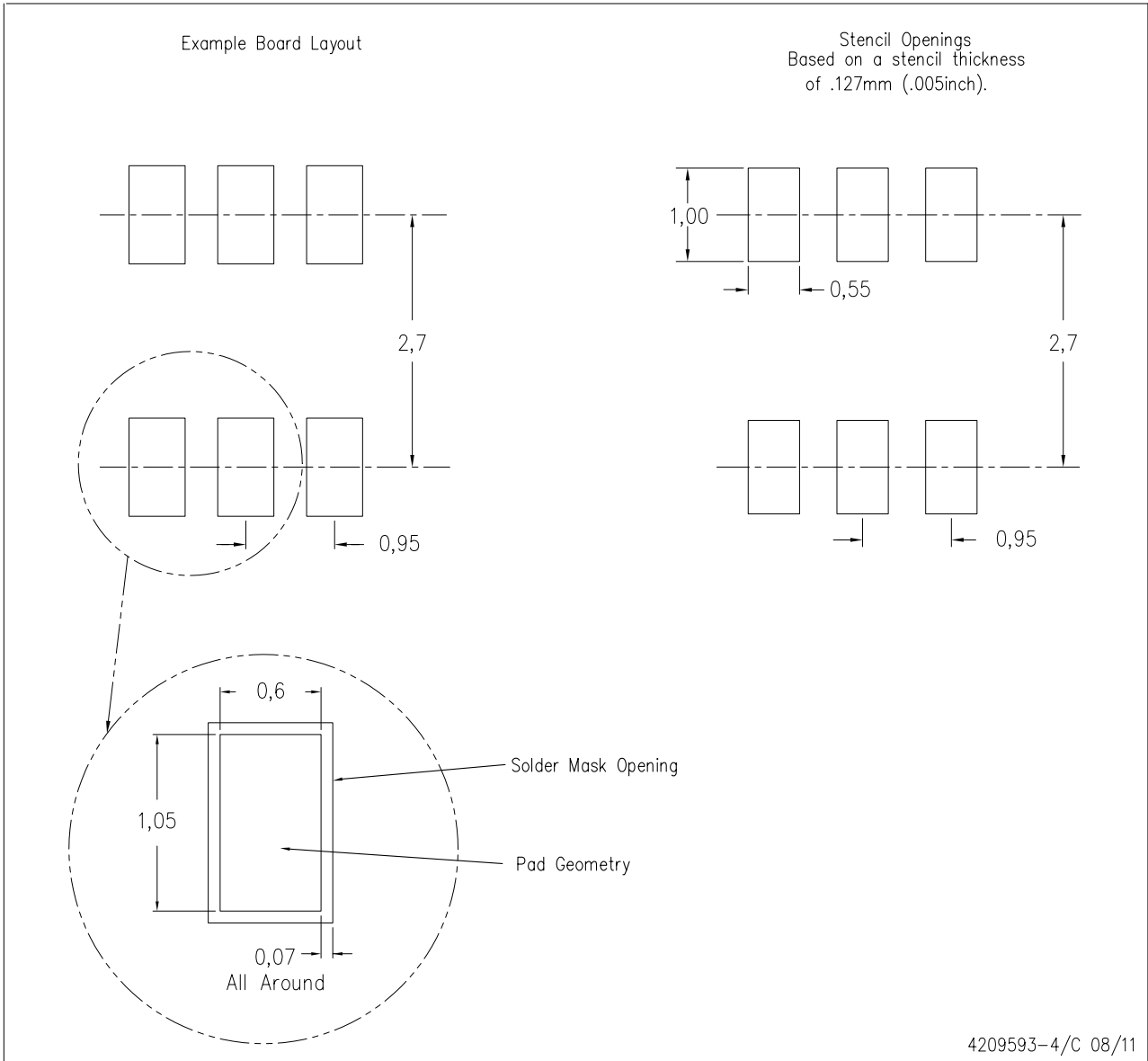


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- △ Falls within JEDEC MO-178 Variation AB, except minimum lead width.

**LAND PATTERN DATA**

DBV (R-PDSO-G6)

PLASTIC SMALL OUTLINE



4209593-4/C 08/11

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

#### Products

|                              |  |
|------------------------------|--|
| Audio                        | <a href="http://www.ti.com/audio">www.ti.com/audio</a>                               |
| Amplifiers                   | <a href="http://amplifier.ti.com">amplifier.ti.com</a>                               |
| Data Converters              | <a href="http://dataconverter.ti.com">dataconverter.ti.com</a>                       |
| DLP® Products                | <a href="http://www.dlp.com">www.dlp.com</a>   |
| DSP                          | <a href="http://dsp.ti.com">dsp.ti.com</a>   |
| Clocks and Timers            | <a href="http://www.ti.com/clocks">www.ti.com/clocks</a>                             |
| Interface                    | <a href="http://interface.ti.com">interface.ti.com</a>                               |
| Logic                        | <a href="http://logic.ti.com">logic.ti.com</a>                                       |
| Power Mgmt                   | <a href="http://power.ti.com">power.ti.com</a>                                       |
| Microcontrollers             | <a href="http://microcontroller.ti.com">microcontroller.ti.com</a>                   |
| RFID                         | <a href="http://www.ti-rfid.com">www.ti-rfid.com</a>                                 |
| OMAP Applications Processors | <a href="http://www.ti.com/omap">www.ti.com/omap</a>                                 |
| Wireless Connectivity        | <a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a> |

#### Applications

|                               |  |
|-------------------------------|--|
| Automotive and Transportation | <a href="http://www.ti.com/automotive">www.ti.com/automotive</a>                         |
| Communications and Telecom    | <a href="http://www.ti.com/communications">www.ti.com/communications</a>                 |
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